



Versatile IO Circuit Schemes for LPDDR4 with 1.8mW/Gbps/pin Power Efficiency

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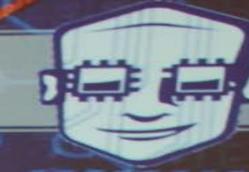
Outline

- Introduction for LPDDR4
- Channel Sensitivity Analysis
- Backward Compatibility
- Summary

Rapid Technology Revolution

DESIGNCON® 2013

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**Robust I/O circuit scheme for world's
first over 1.6Gbps LPDDR3**

Kyoung-Hoi Koo
SAMSUNG

UBM
Electronics



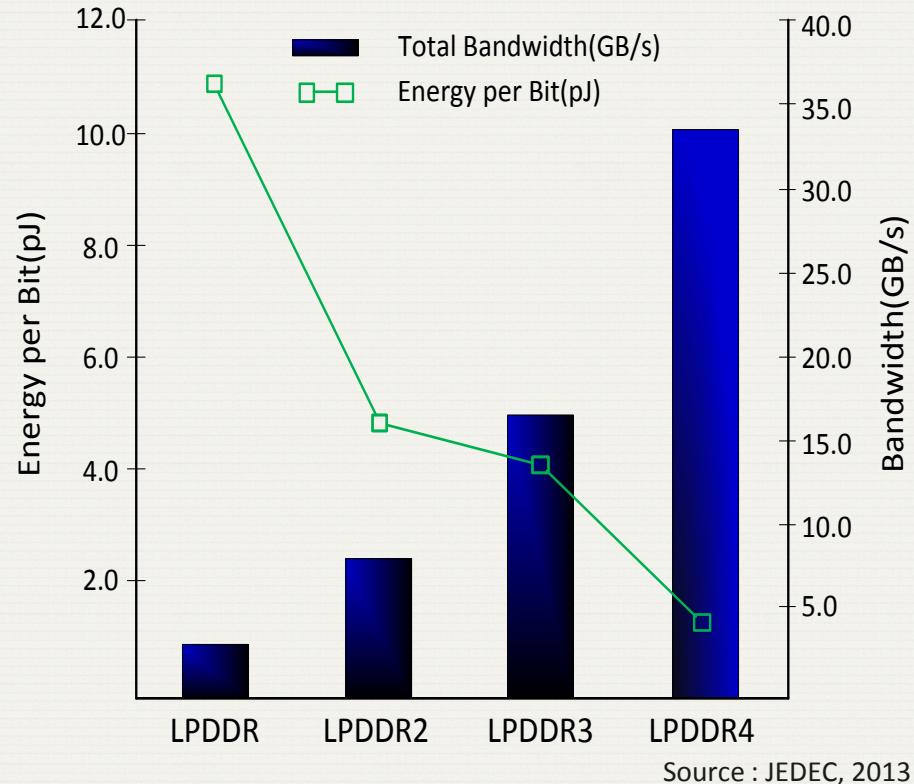
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Mobile DRAM Power Requirements

A great user experience requires great power efficiency

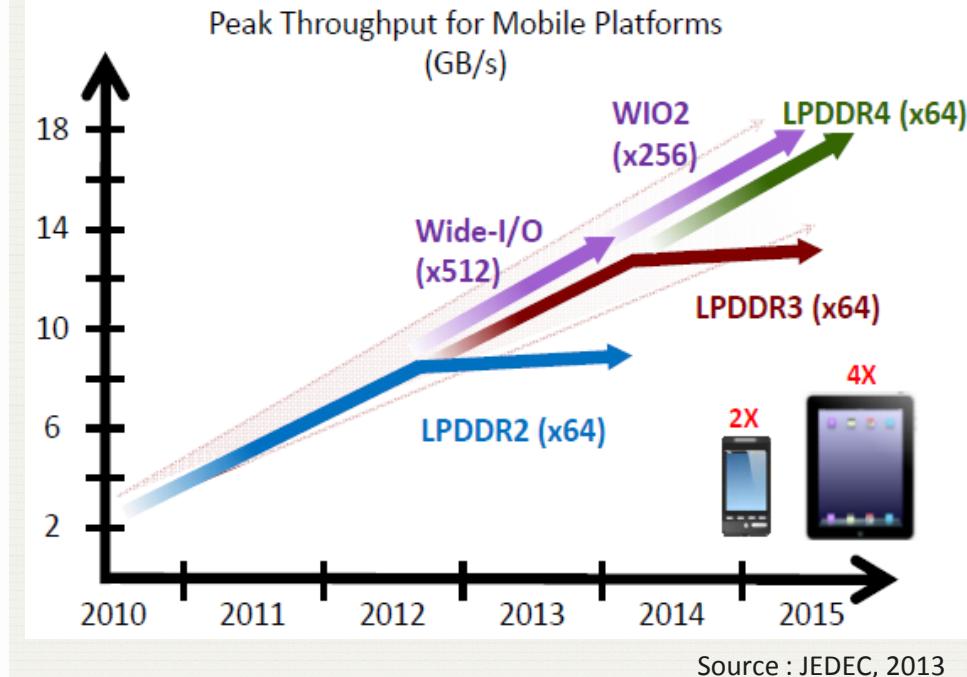
- Phones are targeting 10+ days of standby
- Tablets in ‘connected standby’ targeting 2+ weeks
- Ultrabooks require “always on, always connected” power state, <5 battery drain within 16 hours
- Memory consumes up to 30% of the system power in standby modes



Active and Standby power are critical for mobile platforms

Low Power DRAM Bandwidth

- LPDDR3(x64) BW target is 17 GB/s
 - Evolutionary successor to LPDDR2
 - Data rate up to 2133Mbps DDR
- Wide I/O(x512) BW target is 17GB/s
 - Limited performance scalability
 - Data rate up to 266Mbps SDR
- LPDDR4(x64) BW target is 34GB/s
 - Scalable performance
 - Data rate up to 4.2Gbps DDR
- WIO2(x256) BW target is 34 GB/s
 - Scalable performance
 - Stacked-die configuration(x512, 68GB/s)
 - Data rate up to 1066Mbps DDR

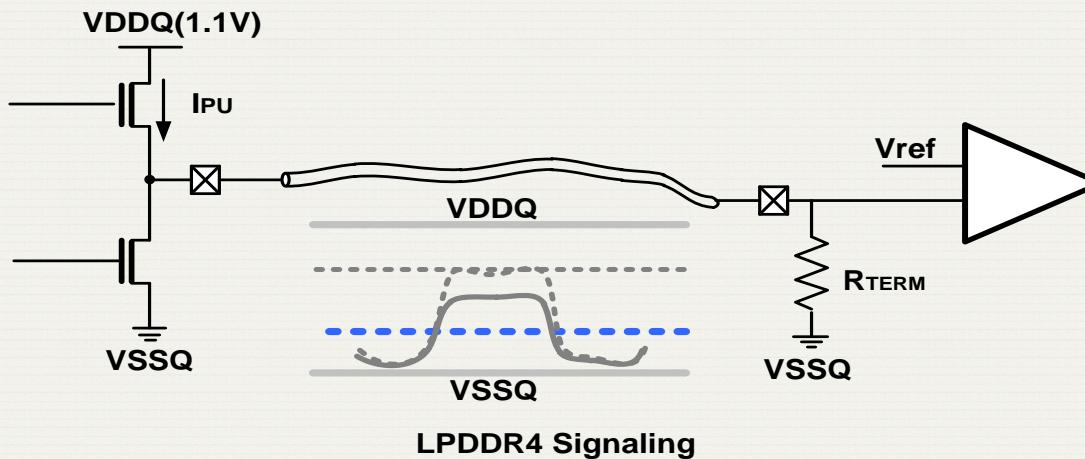
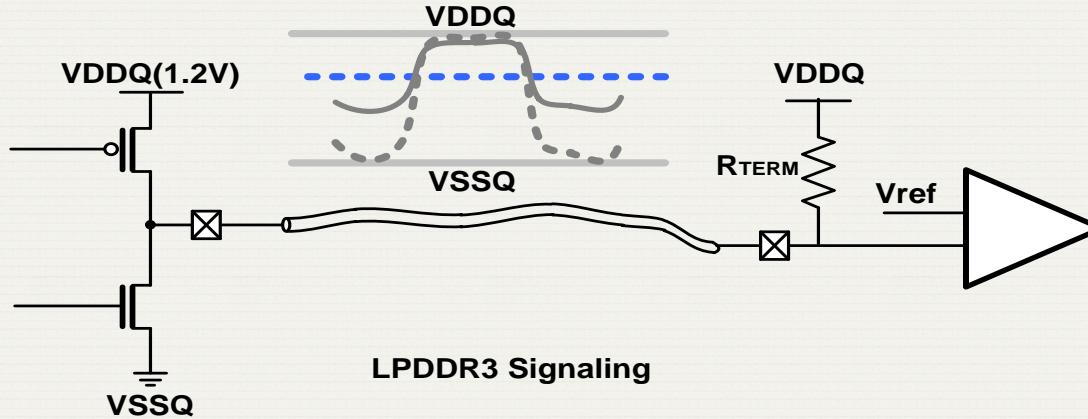


LPDDR4 vs. DDR4 Comparison

Source : JEDEC, 2013

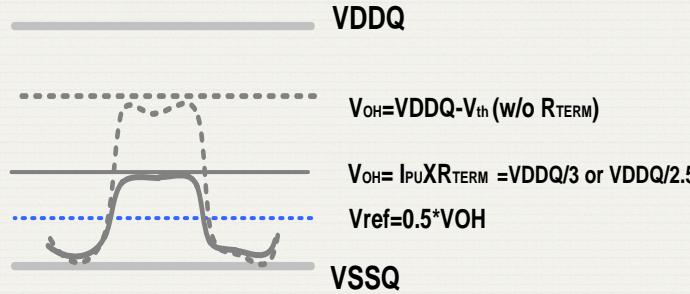
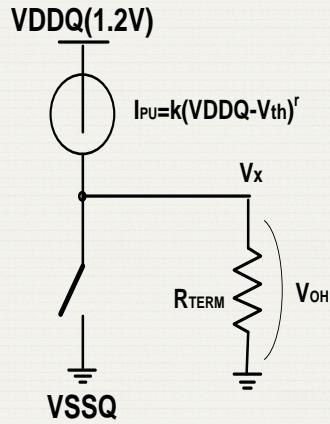
Attribute	LPDDR4	DDR4
Target Market	Mobile Devices	Laptop,PC,Server
Die Architecture	2chX16	1chX16
IO Spec.	~350mV LVSTL	POD_12
DLL in Dram	No	Yes
Termination	VSSQ	VDDQ
Cl/O	<1.0pF	>1.0pF
C/A	6pin SDR CA bus	22pins
Topology	Point-to-point PoP&MCP	DIMM
Max. Frequency	3.2Gbps/4.2Gbps	3.2Gbps
Low Frequency operation	Yes	Yes (DLL off <125MHz)
Target Supply	1.1V(1.0V)	1.2V

Signaling Difference(LP3 vs. LP4)

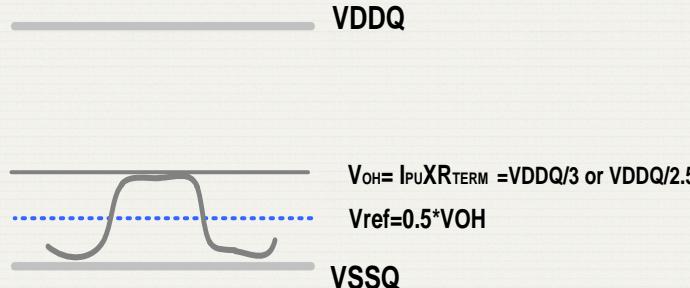
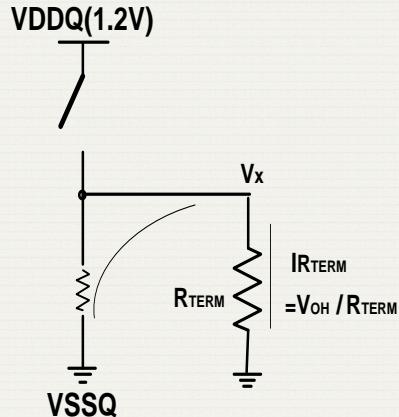


LVSTL Signaling Level

Pull-up drive case

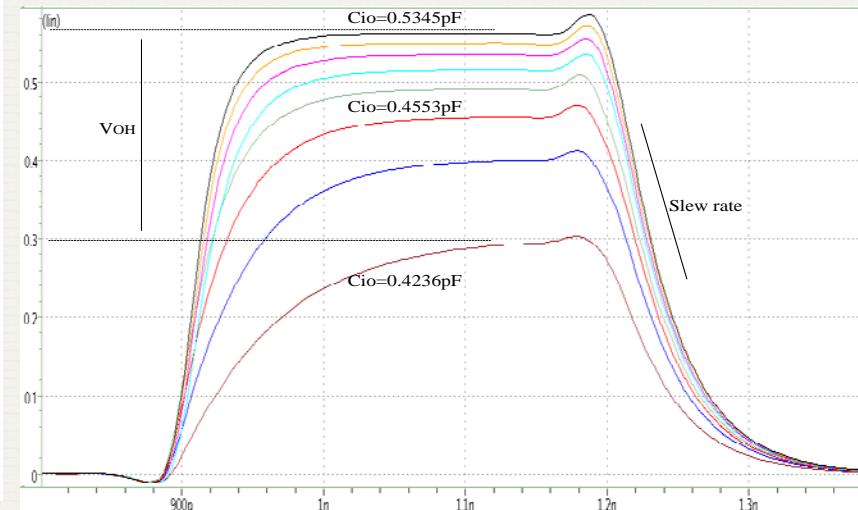
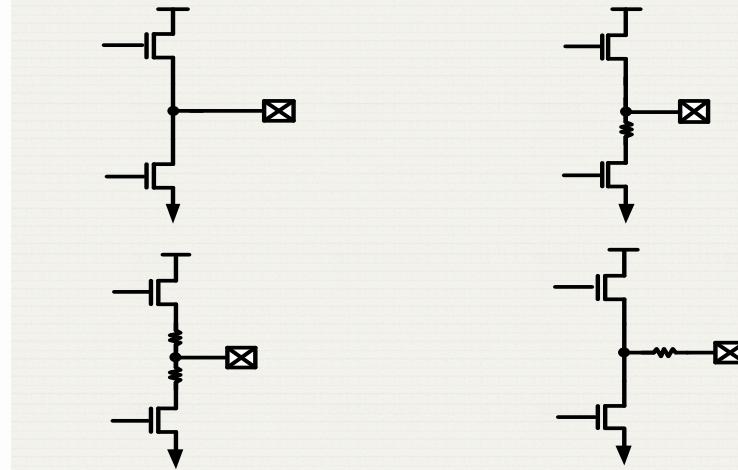


Pull-down drive case



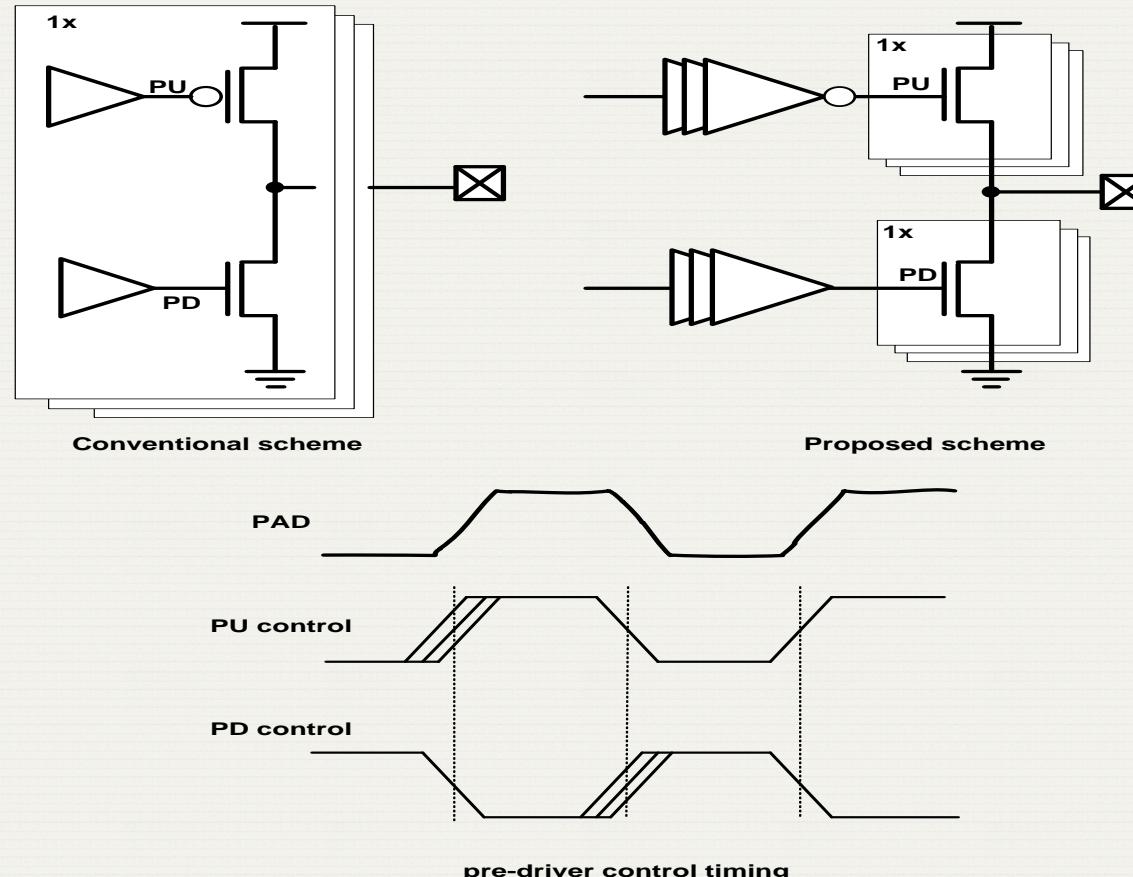
Driver Scheme for Ultra Low Ci/o

- Receiver end Cap. causes signal distortion
- Ci/o portion
 - Driver : ~40%
 - Receiver : ~5%
 - ESD : ~30%
 - Parasitic: ~25%
- Low Ci/o driver scheme
 - Pull-up unit : Voh level
 - Pull-down unit : slew-rate
- Target Ci/o value : 0.5~0.7pF



Special pre-driver/driver Control Scheme

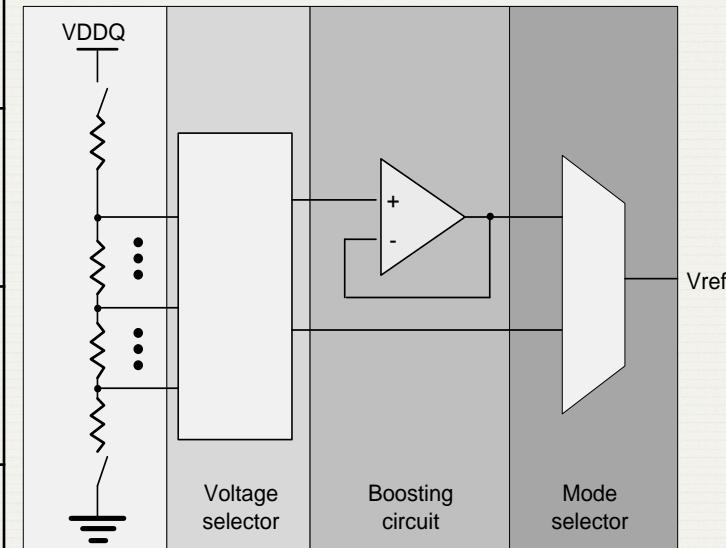
- Proposed scheme for duty balance and minimized SSQN
 - Independent pull-up and pull-down control



Fast Boost Reference Generator

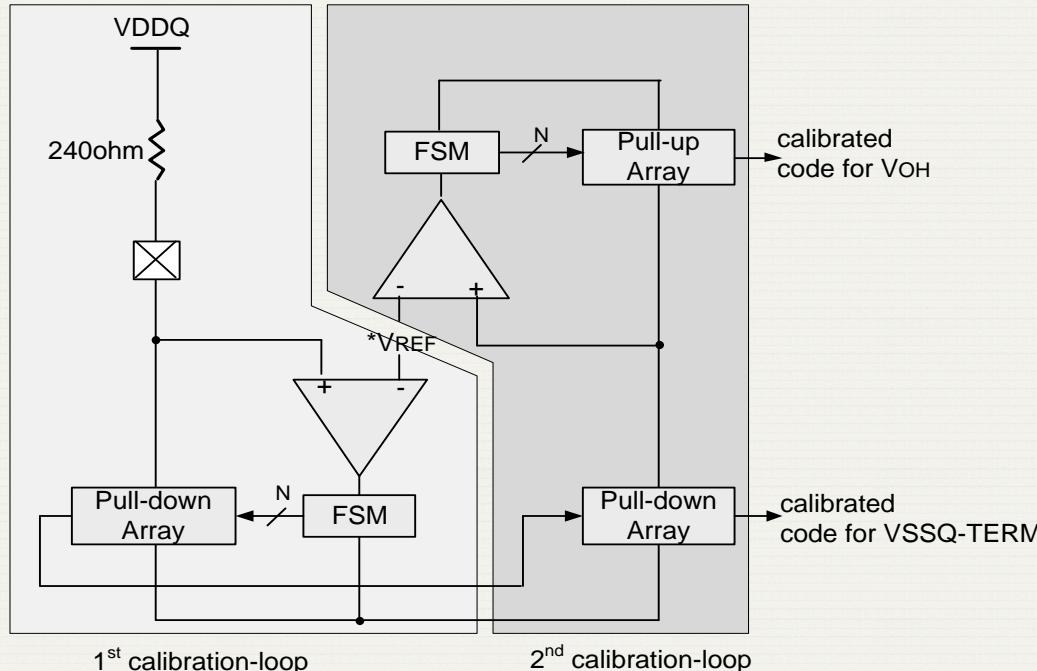
- A wide range reference generator is required to support
 - w/o V_{OH} calibration, w/ V_{OH} calibration, un-termination mode
- Fast setting time for reference voltage change

V _{OH}	Boundary	VDDQ=1.1V	VDDQ=1.0V	Condition
		V _{ref}	V _{ref}	
VDDQ/3	-15%	0.156	0.142	w/ V _{OH} calibration
	15%	0.211	0.192	
VDDQ/2.5	-15%	0.187	0.170	w/o V _{OH} calibration
	15%	0.253	0.230	
VDDQ/3	-30%	0.128	0.117	Un-Termination
	30%	0.238	0.217	
VDDQ/2.5	-30%	0.154	0.140	Un-Termination
	30%	0.286	0.260	
VDDQ-55	VDDQ-0.55	0.275	0.225	
VDDQ-15	VDDQ-0.15	0.475	0.425	



Calibration Circuit

- A wide range reference generator is required to support
 - w/o Voh calibration, w/ Voh calibration, un-termination mode
- Fast setting time for reference voltage change
- Short calibration time for on-time P/V/T variation tracking

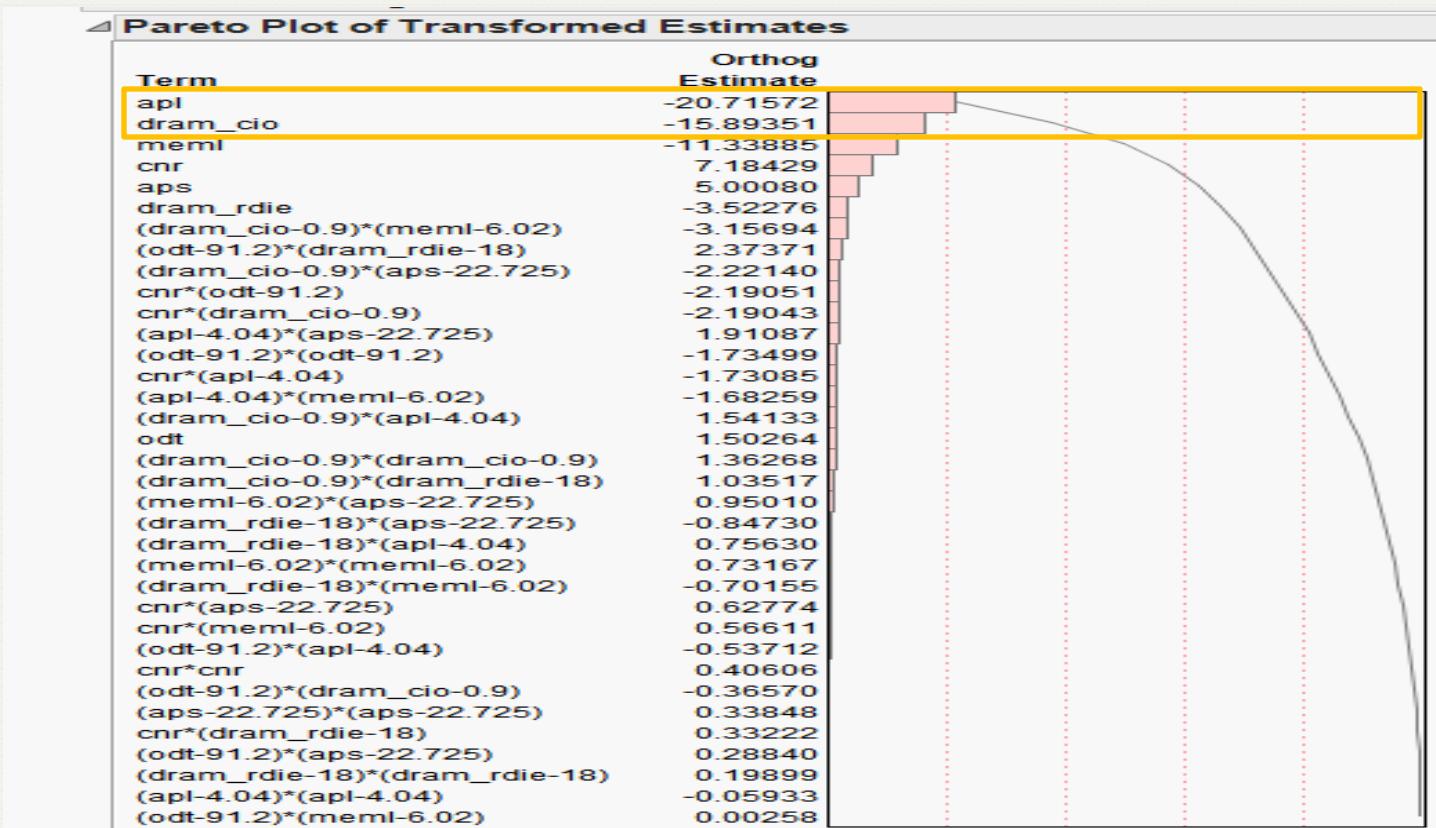


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- Backward Compatibility
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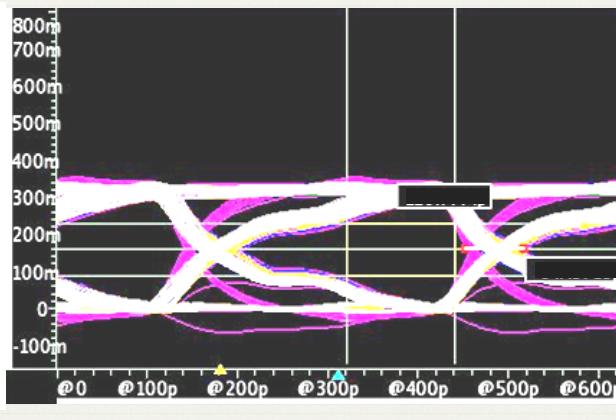
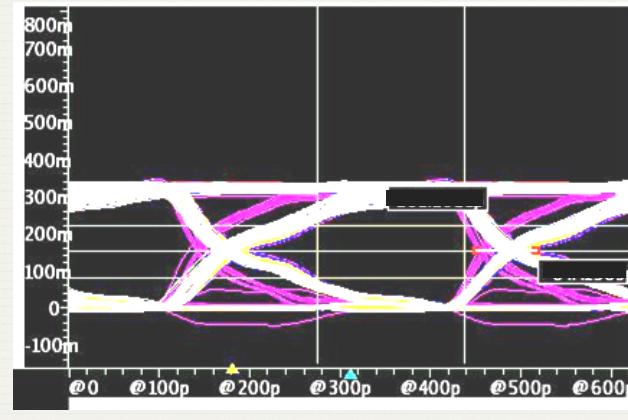
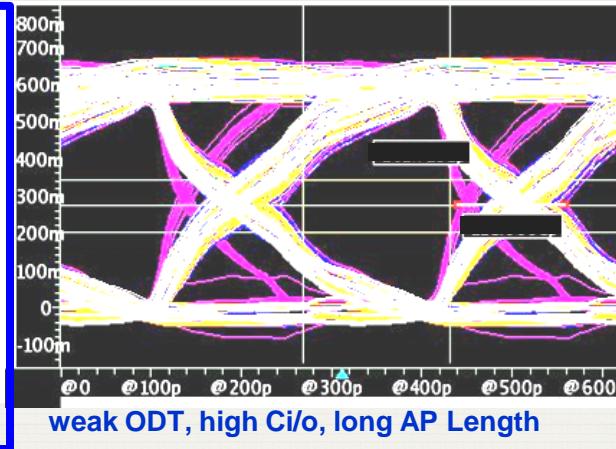
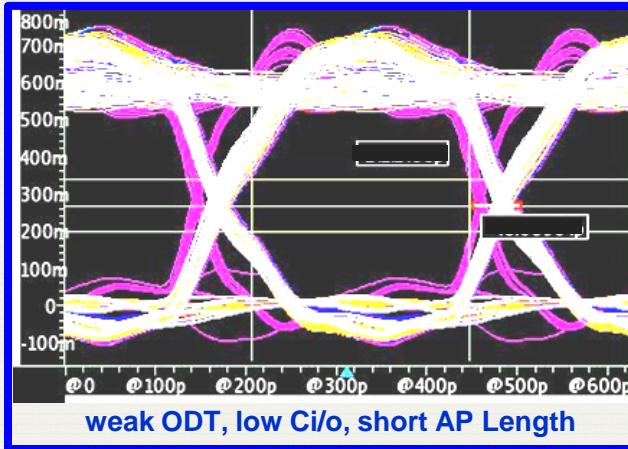
Channel Sensitivity Analysis

- Channel sensitivity analysis using DOE
- PKG length and Ci/o are most sensitive design parameters



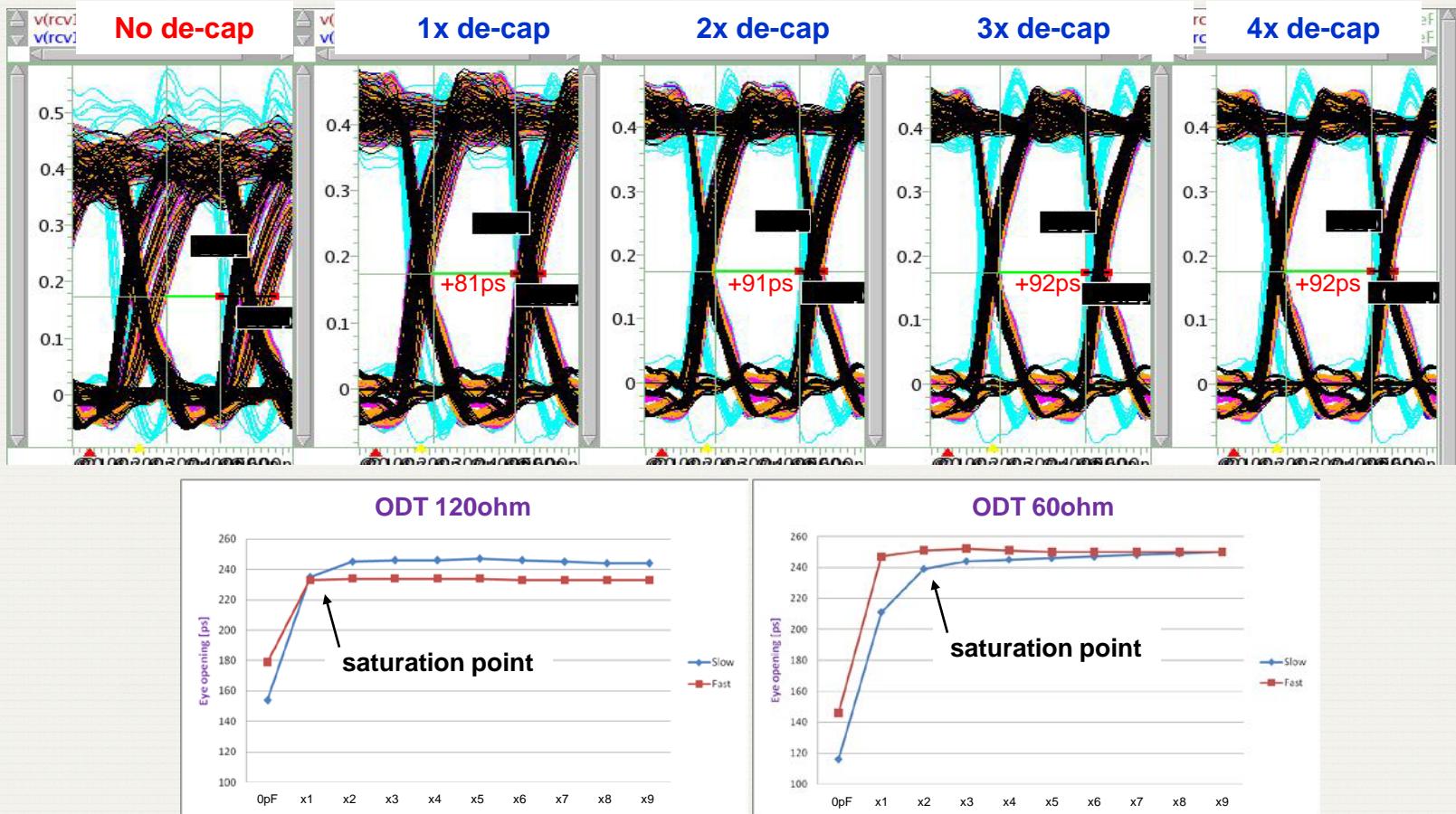
Channel Sensitivity Analysis-cont.

- Considering power consumption weak ODT, low Ci/o is recommend



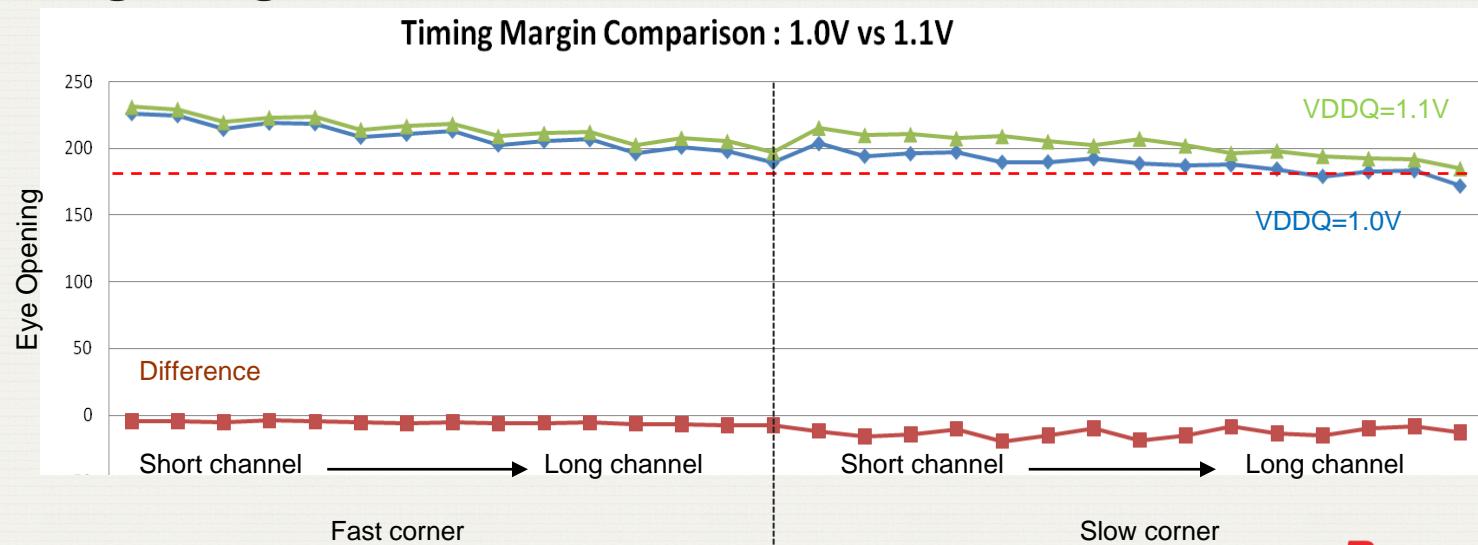
On-die De-cap. Estimation

- Cost effective on-die de-cap estimation method is required



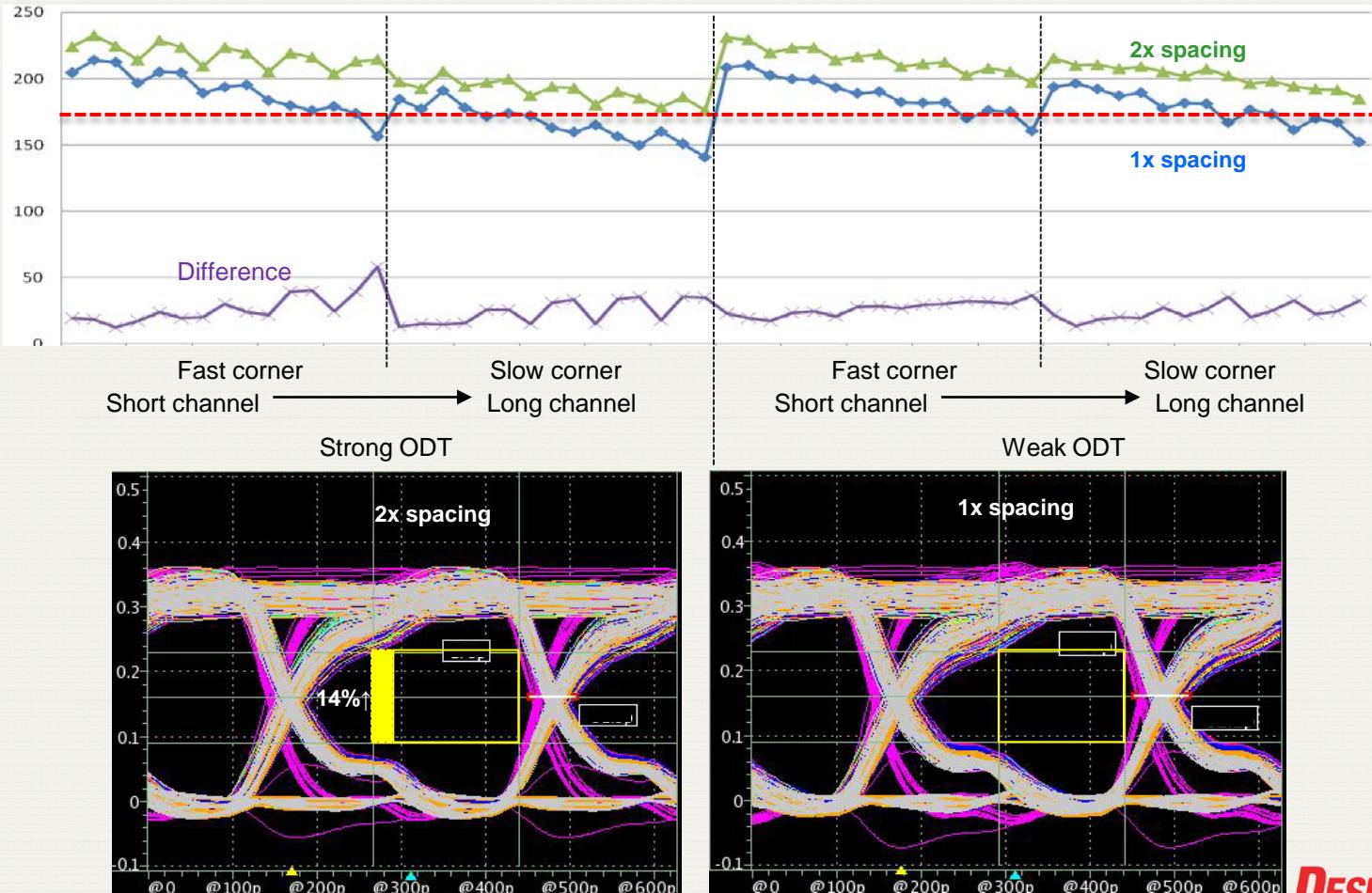
Lower VDDQ Voltage Operation

- For ultra low power consumption, lower VDDQ voltage operation should be verified
 - ~4% timing margin degradation is expected under 1.0V conditions
 - Short channel length (AP-Memory) is required to ensure more timing margin



Case Study for PKG. Spacing

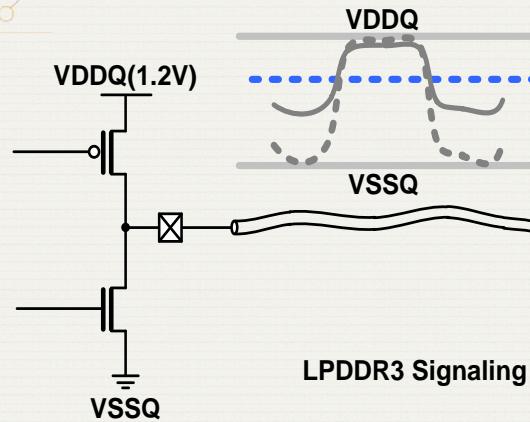
- Wider AP PKG. spacing securing ~14% eye-opening



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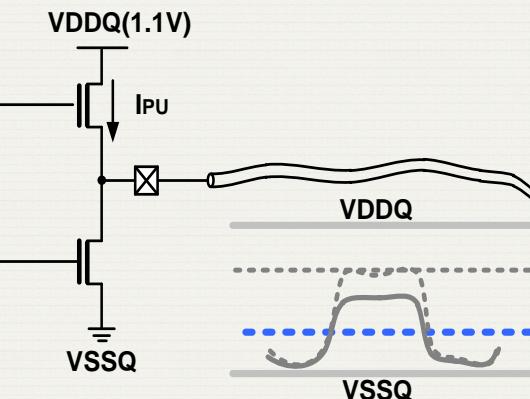
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Signaling Features(LP3 vs. LP4)



LPDDR3 Signaling

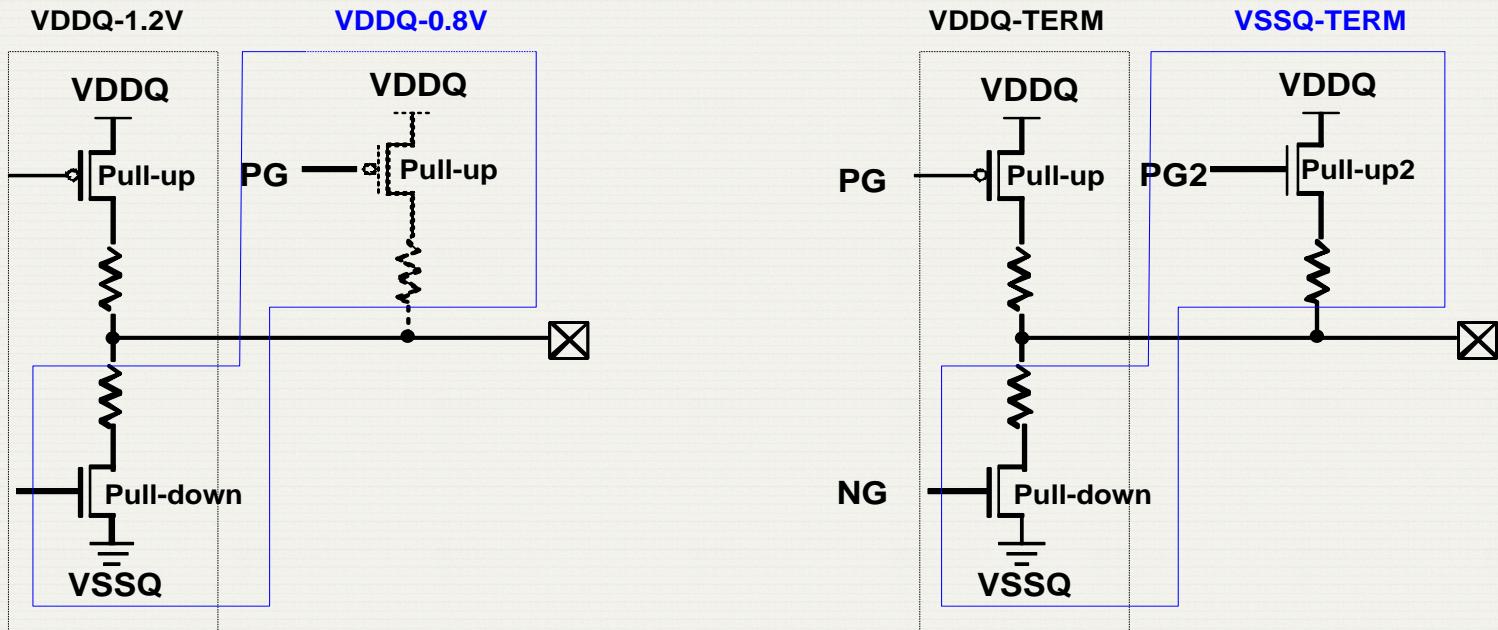
- ✓ PMOS pull-up : large pre-driver size
- ✓ VDDQ Termination
- ✓ Large swing
- ✓ Large current consumption
- ✓ Large SSN & X-talk



LPDDR4 Signaling

- ✓ NMOS pull-up : small pre-driver size
- ✓ $V_{OHmax} = VDDQ - V_{th}$
- ✓ $V_{OH} = I_{pu} * R_{term}$
- ✓ Reduced C_{io}
- ✓ Small swing, small SSN & X-talk

How to Combine LP3/LP4 Driver



- ✓ Change the VDDQ level?
- ✓ Performance degradation
- ✓ Mismatch in signaling level

- ✓ Change the pull-up driver?
- ✓ Area overhead
- ✓ Ci/o increase

Proposed LP3/LP4 Driver Schemes

	Type A	Type B	Type C	Type D
Scheme				
Performance	Pull-up/down matching 			
Power	Cl/o 			
	Dynamic 			
Area	Static 			
	Leakage 			
Cost				

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Summary

- Versatile schemes for 3.2Gbps LPDDR4 interface
 - Ultra low(0.5~0.7pF) Ci/o driver scheme
 - Special pre-driver/driver control scheme
 - Internal Vref. generation with fast boost
 - VSSQ-TERM and Voh calibration
- Channel sensitivity analysis
 - DOE analysis
 - On-die de-cap. estimation
 - Lower VDDQ operation
 - AP PKG. spacing study

Summary-cont.

- Backward Compatibility
 - Differentiated MKT. solution for controller side
 - Proposed LP3/LP4 compatible driver scheme